

EAST Searched

6/22/04 10:41 AM

L Number	Hits	Search Text	DB	Time stamp
1	13	<b>Drussel near Zane.inv.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 14:07</b>
2	387	<b>"Singulation methods" and opening and separating near axis</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 14:23</b>
3	5	<b>"Singulation methods" and opening and separating near axis and cutting near tool</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 14:23</b>
-	2	<b>6664480.pn.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 14:07</b>
-	25	<b>("3780431"   "4316320"   "4426773"   "4532839"   "4621552"   "4742615"   "4791721"   "4926546"   "5311407"   "5448451"   "5483857"   "5488886"   "5521430"   "5652185"   "5773764"   "5831218"   "5854741"   "5886398"   "5894648"   "5960961"   "6047470"   "6114189"   "6239380"   "6246015"   "6342727").PN.</b>	<b>USPAT</b>	<b>2004/06/22 10:14</b>
-	3	<b>"Singulation methods" and 29/\$.ccls. and 174/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 10:16</b>
-	99	<b>"Singulation methods"</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 10:21</b>
-	8476	<b>"Singulation methods" and (74/250; 174/260 ; 174/261 ; 361/760 ; 361/79E ; 361/719; 361/777 ; 361/846 ; 29/841 ; 428/901).ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 14:21</b>
-	2	<b>"Singulation methods" and (74/250; 174/260 ; 174/261 ; 361/760 ; 361/79E ; 361/719; 361/777 ; 361/846 ; 29/841 ; 428/901).ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/22 10:22</b>

-	4	"Singulation methods" and (174/250; 174/260 ; 174/261 ; 361/760 ; 361/79E ; 361/719; 361/777 ; 361/846 ; 29/841 ; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:23
-	3	"Singulation methods" and (174/250; 174/260 ; 174/261 ; 361/760 ; 361/79E ; 361/719; 361/777 ; 361/846 ; 29/841 ; 428/901).ccls. and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 10:23

	<b>Title</b>	<b>Current OR</b>
<b>1</b>	<b>Use of a reference fiducial on a semiconductor package to monitor and control a singulation method</b>	<b>438/401</b>
<b>2</b>	<b>Singulation methods and substrates for use with same</b>	<b>29/846</b>
<b>3</b>	<b>Method for determining the location of a droplet on a component</b>	<b>438/14</b>
<b>4</b>	<b>Use of a reference fiducial on a semiconductor package to monitor and control a singulation method</b>	<b>438/460</b>
<b>5</b>	<b>Singulation methods and substrates for use with same</b>	<b>174/250</b>
<b>6</b>	<b>Method for establishing reference coordinates for a point on a component</b>	<b>438/16</b>
<b>7</b>	<b>Use of a reference fiducial on a semiconductor package to monitor and control a singulation method</b>	<b>257/708</b>
<b>8</b>	<b>Singulation methods and substrates for use with same</b>	<b>174/255</b>
<b>9</b>	<b>Method for determining the concentration of contamination on a component</b>	<b>438/14</b>
<b>10</b>	<b>Method for establishing reference coordinates for a point on a component</b>	<b>438/14</b>
<b>11</b>	<b>Singulation methods and substrates for use with same</b>	<b>174/250</b>
<b>12</b>	<b>Singulation methods</b>	<b>29/847</b>

	<b>Title</b>	<b>Current OR</b>
<b>13</b>	<b>Apparatus for establishing reference coordinates for a point on a component</b>	<b>118/712</b>

	<b>Current XRef</b>
<b>1</b>	<b>438/462</b>
<b>2</b>	<b>174/250; 174/255; 29/831</b>
<b>3</b>	
<b>4</b>	<b>438/401</b>
<b>5</b>	<b>174/268; 257/E23.004</b>
<b>6</b>	
<b>7</b>	<b>257/797</b>
<b>8</b>	<b>257/E23.004; 29/846; 361/771</b>
<b>9</b>	
<b>10</b>	
<b>11</b>	<b>257/E23.004; 29/841; 29/846; 361/719; 361/766; 361/792; 428/901</b>
<b>12</b>	<b>29/412; 29/415; 29/846; 83/35</b>